



Case: AMKOR-045A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suk Sing Jang

Serial No.: 09/687,493

Filed: 10/13/2000

For: Semiconductor Package Having Improved
Adhesiveness and Ground Bonding

) Group No.: 2826

) Examiner:
) Williams, Alexander

#17/B
Cn to Drafts
And
Jmiller
6/25/03

RESPONSE TO OFFICE ACTION

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Office Action mailed March 6, 2003, in relation to the above-
identified patent application, please amend the application as follows:

RECEIVED
JUN 12 2003
TECHNOLOGY CENTER 2800